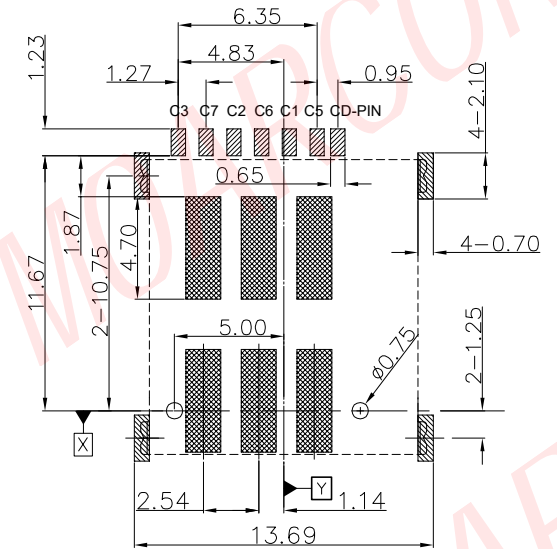
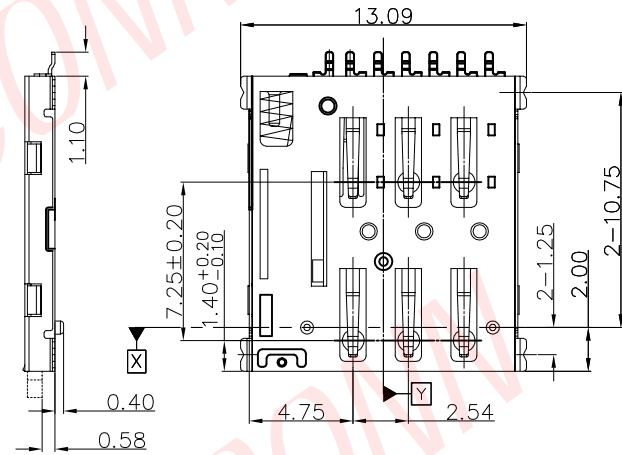
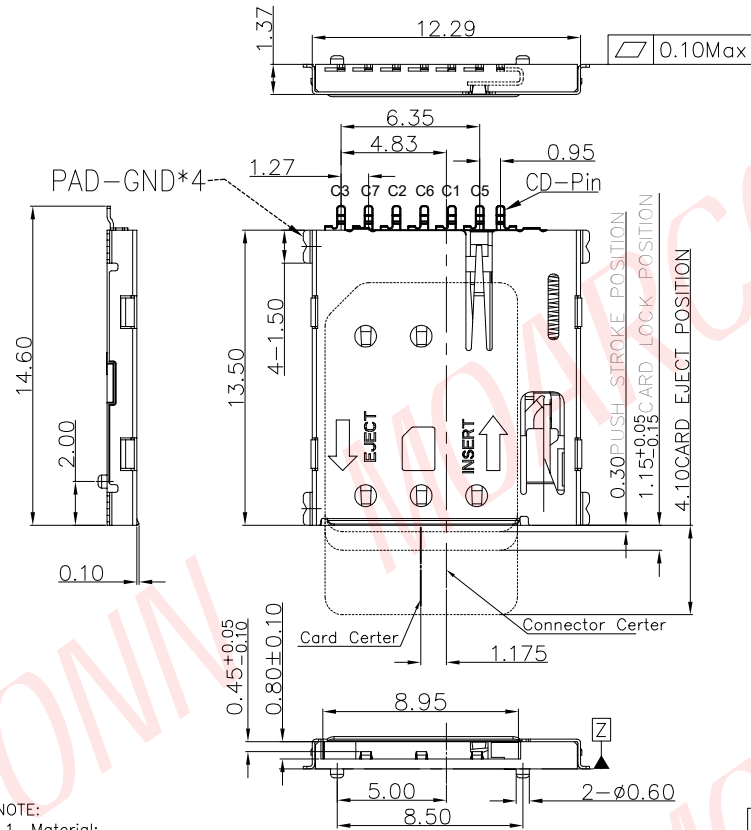
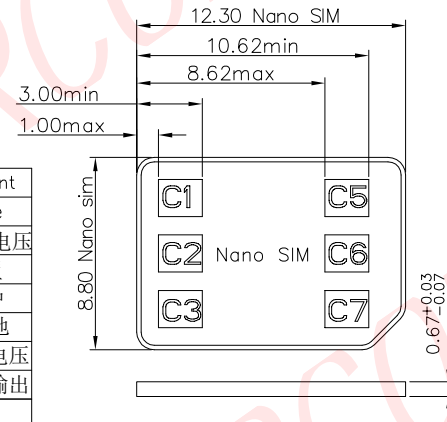
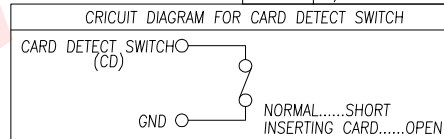


All materials, plating and process meet HF requirements.

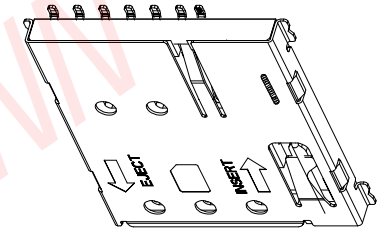


- NOTE:
- Material:
 - 1-1 Housing: High Temperature Thermoplastic, (LCP S475) Color Black UL 94V-0
 - 1-2 Contact: Phosphor Bronze (C5210R-H, T=0.15±0.01mm)
 - 1-3 Cover: SUS301-H T=0.12±0.03mm
 - Plating:
 - 2-1 Contact terminal:
 - Contact area: Gold 1u" Min.
 - Solder area: Gold 0.8u" Min.
 - Underplating: Ni overall 50u" Min.
 - 2-2 Cover:
 - Underplating: Ni overall 50u" Min.
 - Solder area: Gold 0.8u" Min.
 - Specification:
 - 3-1. Current Rating : 0.5mA AC/DC max.
 - 3-2. Voltage Rating : 125V AC/DC
 - 3-3. Ambient Temperature Range : -20°C~+60°C
 - 3-4. Storage Temperature Range : -40°C~+70°C
 - 3-5. Ambient Humidity Range : 95% R.H. Max.
 - 3-6. Contact Resistance: 100m max.
 - 3-7. Insulation Resistance: 1000M min./500VDC
 - 3-8. Mating Cycles: 3000 Insertions

SIM pin assignment	
PIN#	Name
C1	VCC供电电压
C2	RST重置
C3	CLK时钟
C5	GND接地
C6	VPP程序电压
C7	I/O输入输出



- PAD AREA
 - KEEP OUT AREA
 - GND PATTERN ONLY
 - NO COPPER AREA (NO Trace&Via&GND)
- RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE
X0	----	NEW RELEASE	Aaron	2023.01.07

MOARCONN MORE CONNECTIONS SMARTE FUTURE		DONG GUAN MOARCONN ELECTRONIC Co., Ltd.			
DIMENSIONS INIT: mm UNLESS OTHERWISE SPECIFIABLE	DIMENSION	TOLERANCE	PRODUCT NAME : NANO SIM CARD CONN. PUSH TYPE H1.35mm	DRAWING: Aaron	DATE: 2023.01.07
	X.X: ± 0.35 X.XX: ± 0.20 X.XXX: ± 0.10 ANGULAR: ± 2'		PRODUCT NO. : NS135-T1151-01	CHECK:	DATE:
			DRAWING NO. : D-NS135-T1151-01	APPROVED:	DATE:
				SCALE: 1:1	DWG ID: C D
				REV.: X0	PAGE: 1 OF 1